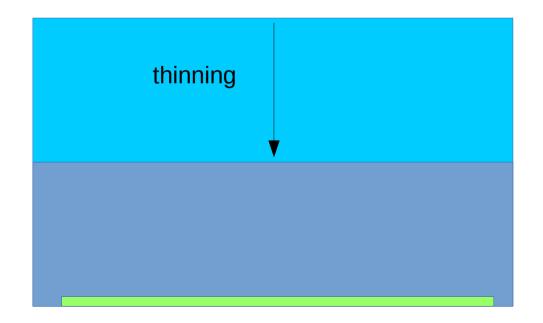


High resistivity wafer (p) ~1e12

Thick enough for backside implantation

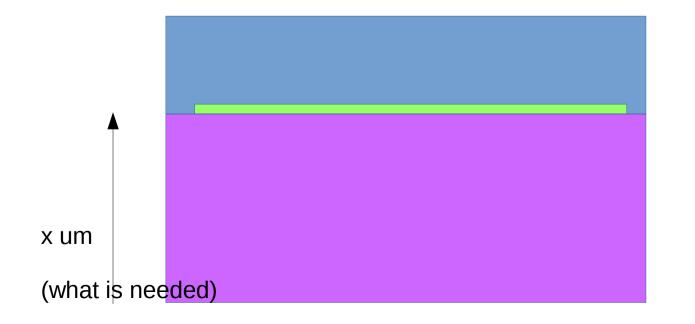


Backside implantation (p+) ~1e15

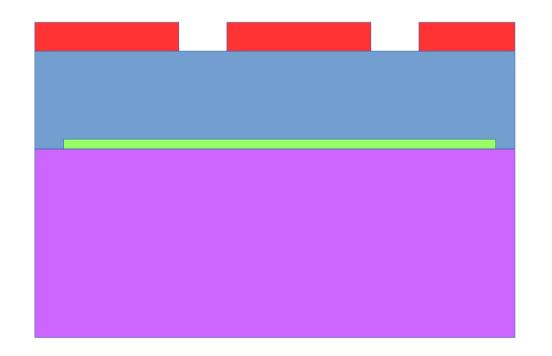




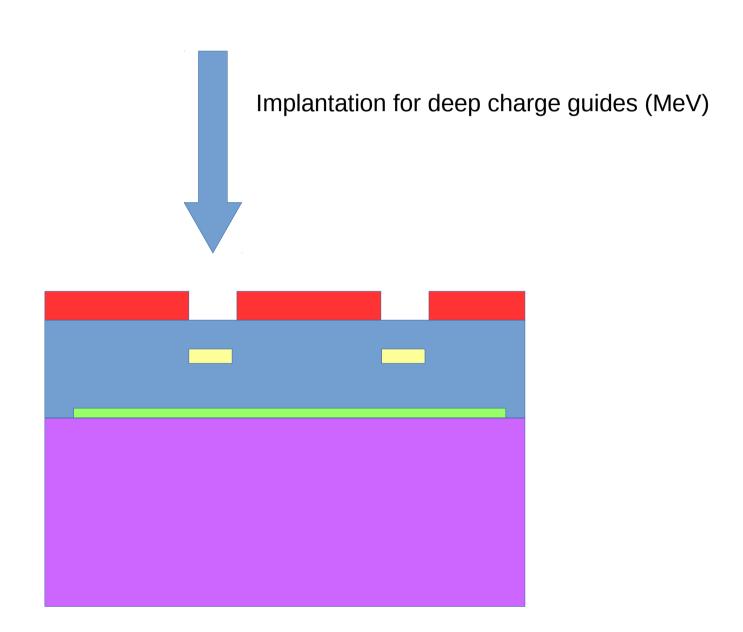
Do this before thinning?!

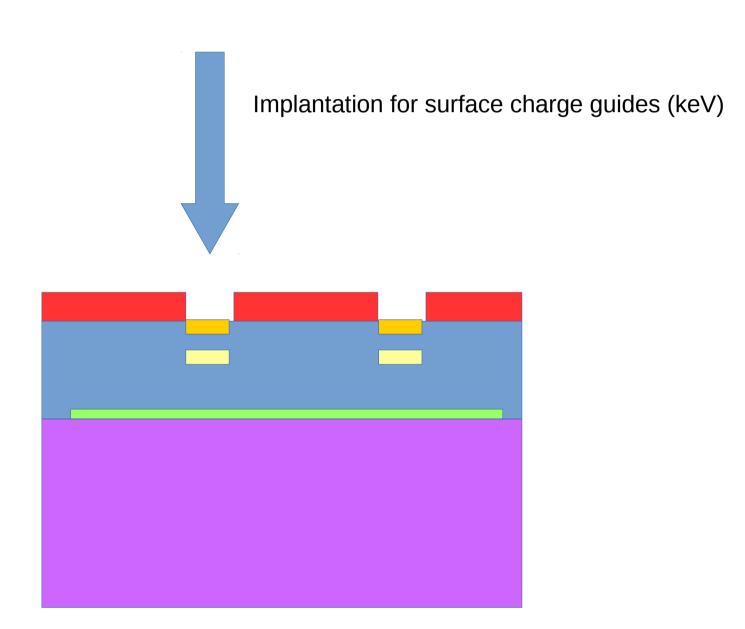


Temperature bond handle wafer

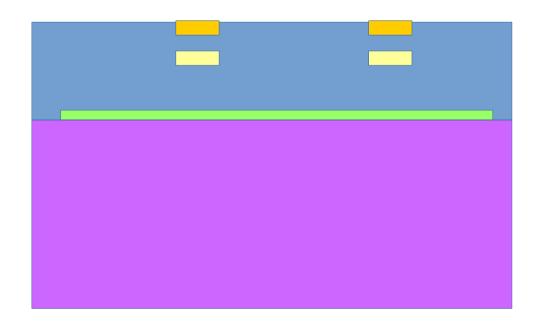


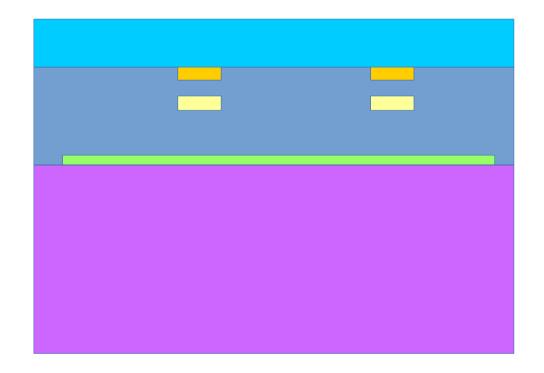
mask





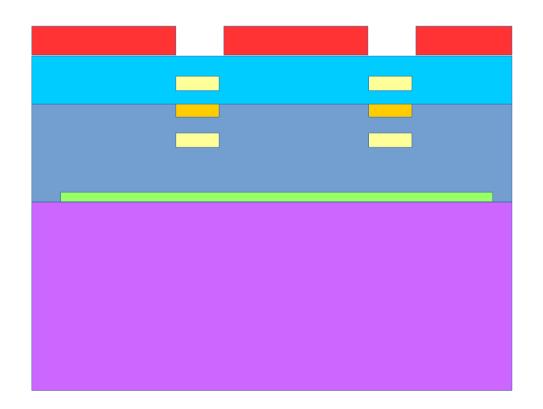
Mask removal



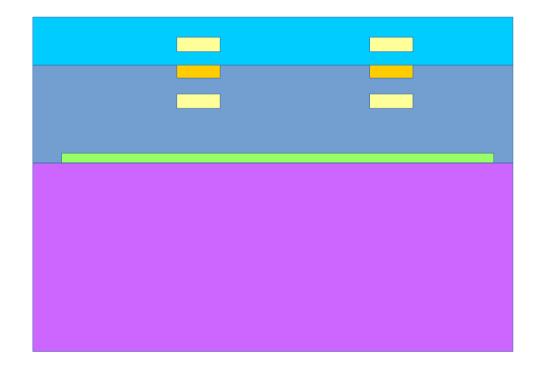


Epi overgrowth (p) n = ~1e13 (lower if possible) Apply mask.

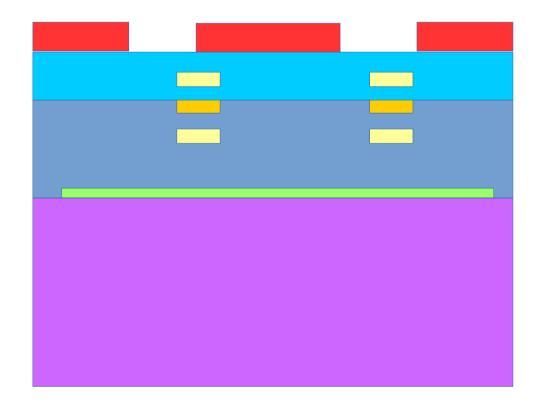
Implantation for deep charge guides (MeV)

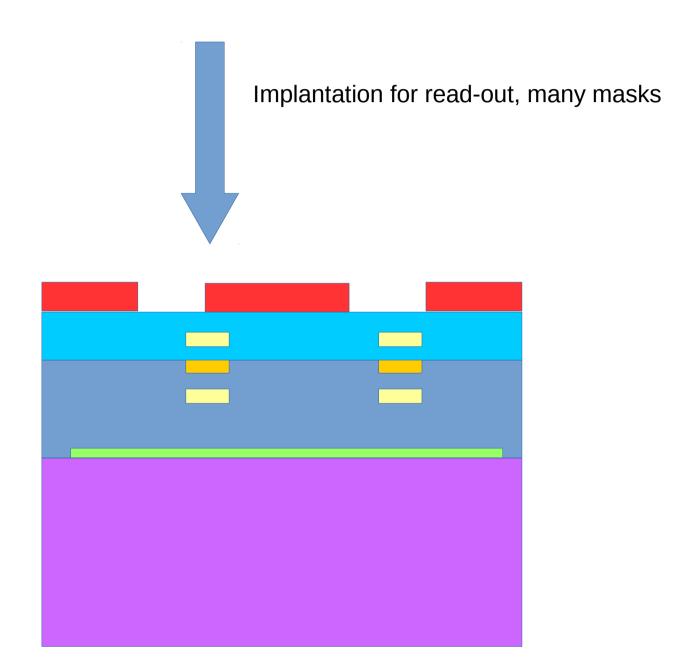


Mask removal



Mask for read-out (TimePix3); many masks





Mask removal

